

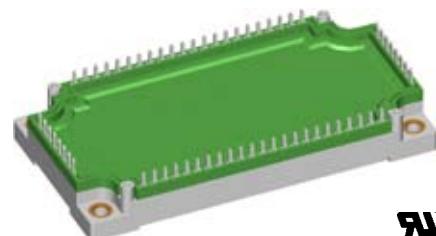
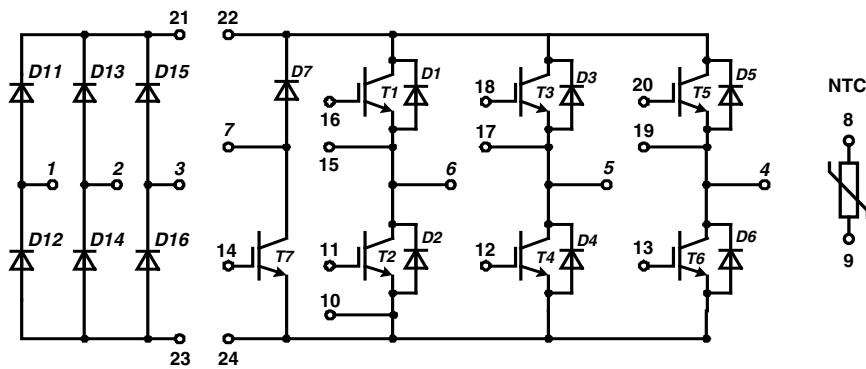
Converter - Brake - Inverter Module

XPT IGBT

Single Phase Rectifier	Brake Chopper	Three Phase Inverter
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAVM25} = 390 \text{ A}$	$I_{C25} = 60 \text{ A}$	$I_{C25} = 120 \text{ A}$
$I_{FSM} = 1100 \text{ A}$	$V_{CE(sat)} = 1.8 \text{ V}$	$V_{CE(sat)} = 1.8 \text{ V}$

Part name (Marking on product)

MIXA80WB1200TEH



E 72873

Pin configuration see outlines.

Features:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design
(Xtreme light Punch Through) results in:
 - short circuit rated for 10 μsec .
 - very low gate charge
 - square RBSOA @ 3x I_C
 - low EMI
- Thin wafer technology combined with the XPT design results in a competitive low $V_{CE(sat)}$
- SONIC™ diode
 - fast and soft reverse recovery
 - low operating forward voltage

Application:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies

Package:

- "E3-Pack" standard outline
- Insulated copper base plate
- Soldering pins for PCB mounting
- Temperature sense included

Output Inverter T1 - T6

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
V_{GES}	max. DC gate voltage	continuous		± 20		V
V_{GEM}	max. transient collector gate voltage	transient		± 30		V
I_{C25}	collector current	$T_c = 25^\circ C$		120		A
I_{C80}		$T_c = 80^\circ C$		84		A
P_{tot}	total power dissipation	$T_c = 25^\circ C$		390		W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_c = 77 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_c = 3 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.5	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.03 0.6	0.2	mA mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_c = 75 A$		230		nC
$t_{d(on)}$	turn-on delay time	$\left. \begin{array}{l} t_r \\ t_{d(off)} \\ t_f \\ E_{on} \\ E_{off} \end{array} \right\}$ inductive load $V_{CE} = 600 V; I_c = 75 A$ $V_{GE} = \pm 15 V; R_G = 10 \Omega$	$T_{VJ} = 125^\circ C$	70		ns
t_r	current rise time			40		ns
$t_{d(off)}$	turn-off delay time			250		ns
t_f	current fall time			100		ns
E_{on}	turn-on energy per pulse			6.8		mJ
E_{off}	turn-off energy per pulse			8.3		mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 10 \Omega;$	$T_{VJ} = 125^\circ C$ $V_{CEK} = 1200 V$		225	A
SCSOA	short circuit safe operating area					
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$	$T_{VJ} = 125^\circ C$		10	μs
I_{sc}	short circuit current	$R_G = 10 \Omega$; non-repetitive		300		A
R_{thJC}	thermal resistance junction to case	(per IGBT)			0.32	K/W

Output Inverter D1 - D6

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200		V
I_{F25}	forward current	$T_c = 25^\circ C$		135		A
I_{F80}		$T_c = 80^\circ C$		90		A
V_F	forward voltage	$I_F = 100 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.85	2.2	V
Q_{rr}	reverse recovery charge	$\left. \begin{array}{l} I_{RM} \\ \text{max. reverse recovery current} \\ t_{rr} \\ \text{reverse recovery time} \\ E_{rec} \end{array} \right\}$ $V_R = 600 V$ $di_F/dt = -1200 A/\mu s$ $I_F = 100 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	-		μC
I_{RM}	max. reverse recovery current			-		A
t_{rr}	reverse recovery time			-		ns
E_{rec}	reverse recovery energy			-		mJ
R_{thJC}	thermal resistance junction to case	(per diode)			0.4	K/W

 $T_c = 25^\circ C$ unless otherwise stated

Brake T7

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
V_{GES}	max. DC gate voltage	continuous		± 20		V
V_{GEM}	max. transient collector gate voltage	transient		± 30		V
I_{C25}	collector current	$T_C = 25^\circ C$	60		A	
I_{C80}		$T_C = 80^\circ C$	40		A	
P_{tot}	total power dissipation	$T_C = 25^\circ C$		195		W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 35 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 1.5 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.5	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.01 0.1	0.1	mA mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 35 A$		107		nC
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	turn-on delay time current rise time turn-off delay time current fall time turn-on energy per pulse turn-off energy per pulse	inductive load $V_{CE} = 600 V; I_C = 35 A$ $V_{GE} = \pm 15 V; R_G = 27 \Omega$	$T_{VJ} = 125^\circ C$	70 40 250 100 3.8 4.1		ns ns ns ns mJ mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 27 \Omega;$ $V_{CEK} = 1200 V$	$T_{VJ} = 125^\circ C$		105	A
SCSOA	short circuit safe operating area					
t_{sc} I_{sc}	short circuit duration short circuit current	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$ $R_G = 27 \Omega$; non-repetitive	$T_{VJ} = 125^\circ C$		10	μs
R_{thJC}	thermal resistance junction to case	(per IGBT)			0.64	K/W

Brake Chopper D7

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200		V
I_{F25}	forward current	$T_C = 25^\circ C$	44		A	
I_{F80}		$T_C = 80^\circ C$	29		A	
V_F	forward voltage	$I_F = 30 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.85	2.2	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.01 0.15	0.1	mA mA
Q_{rr} I_{RM} t_{rr} E_{rec}	reverse recovery charge max. reverse recovery current reverse recovery time reverse recovery energy	$V_R = 600 V$ $di_F/dt = tbd A/\mu s$ $I_F = 30 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	tbd tbd tbd tbd		μC A ns μJ
R_{thJC}	thermal resistance junction to case	(per diode)			1.2	K/W

 $T_C = 25^\circ C$ unless otherwise stated

Input Rectifier Bridge D11 - D16

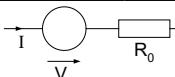
Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage		$T_{VJ} = 25^\circ\text{C}$		1600	V
I_{FAV}	average forward current	sine 180°	$T_C = 80^\circ\text{C}$		94	A
I_{DAVM}	max. average DC output current	rect.; $d = 1/3$	$T_C = 80^\circ\text{C}$		265	A
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1100 970	A A
I^2t	I^2t value for fusing	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		6000 4700	A ² s A ² s
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$		250	W
V_F	forward voltage	$I_F = 150 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.3 1.3	1.6	V V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.05 2.0	0.1	mA mA
R_{thJC}	thermal resistance junction to case	(per diode)			0.5	K/W

Temperature Sensor NTC

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
R_{25}	resistance		$T_C = 25^\circ\text{C}$	4.75	5.0	kΩ
$B_{25/50}$					3375	K

Module

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
T_{VJ}	operating temperature		-40		125	°C
T_{VJM}	max. virtual junction temperature				150	°C
T_{stg}	storage temperature		-40		125	°C
V_{ISOL}	isolation voltage	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			3000	V~
CTI	comparative tracking index				-	
M_d	mounting torque (M5)		3		6	Nm
d_s	creep distance on surface		6			mm
d_A	strike distance through air		6			mm
$R_{pin-chip}$	resistance pin to chip				5	mΩ
R_{thCH}	thermal resistance case to heatsink	with heatsink compound		0.01		K/W
Weight				300		g

Equivalent Circuits for Simulation

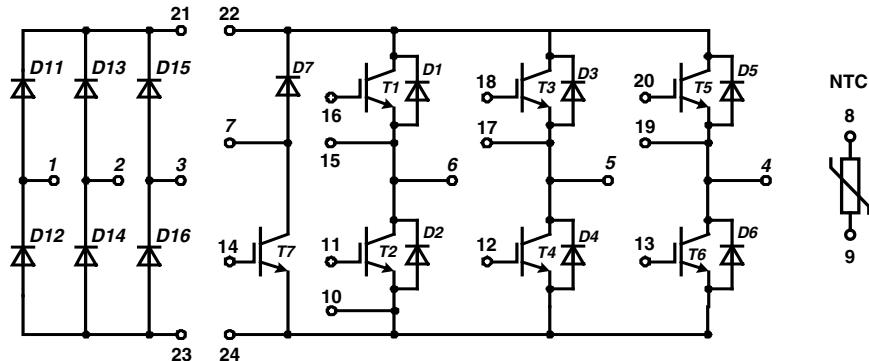
Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_0	rectifier diode	D8 - D13	$T_{VJ} = 150^\circ\text{C}$		0.87 2.7	V mΩ
R_0						
V_0	IGBT	T1 - T6	$T_{VJ} = 150^\circ\text{C}$		1.1 17.9	V mΩ
R_0						
V_0	free wheeling diode	D1 - D6	$T_{VJ} = 150^\circ\text{C}$		1.09 9.1	V mΩ
R_0						
V_0	IGBT	T7	$T_{VJ} = 150^\circ\text{C}$		1.1 40	V mΩ
R_0						
V_0	free wheeling diode	D7	$T_{VJ} = 150^\circ\text{C}$		1.2 27.0	V mΩ
R_0						

$T_C = 25^\circ\text{C}$ unless otherwise stated

IXYS reserves the right to change limits, test conditions and dimensions.

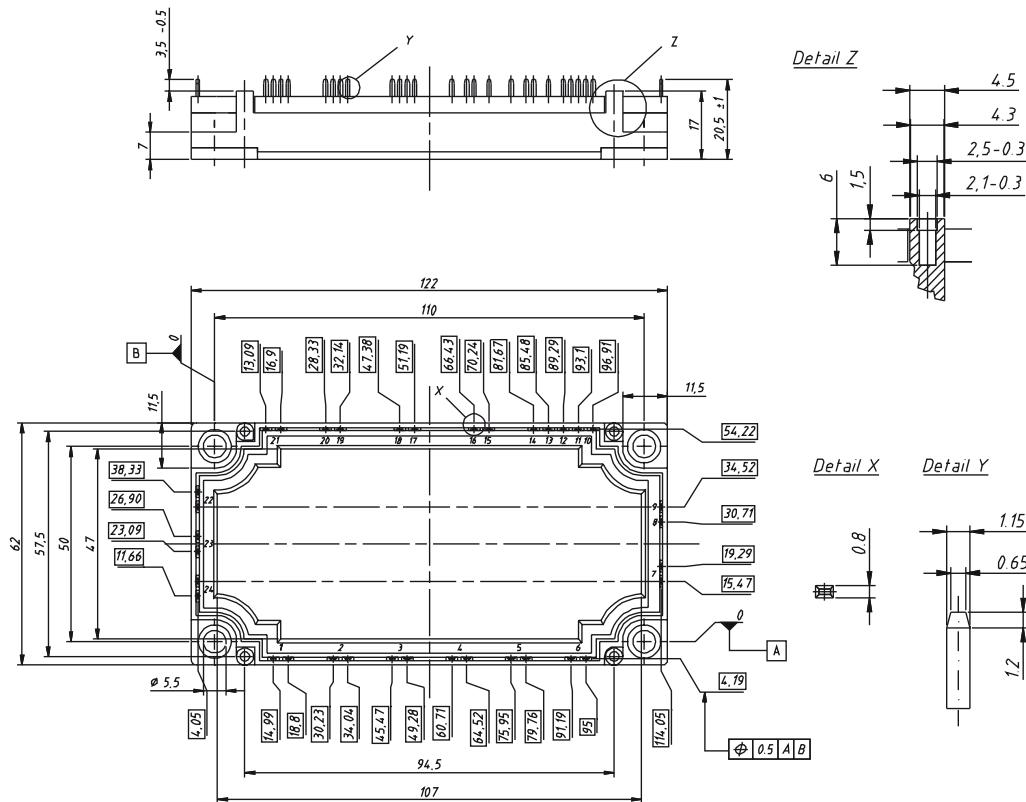
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Circuit Diagram

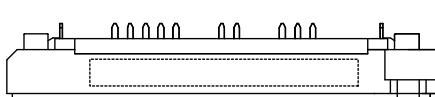


Outline Drawing

Dimensions in mm (1 mm = 0.0394")



Product Marking



Part number

M = Module
 I = IGBT
 XA = XPT standard
 80 = Current Rating [A]
 WB = 6-Pack + 3~ Rectifier Bridge & Brake Unit
 1200 = Reverse Voltage [V]
 T = NTC
 EH = E3-Pack

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MIXA80WB1200 TEH	MIXA80WB1200TEH	Box	6	509112

IXYS reserves the right to change limits, test conditions and dimensions.

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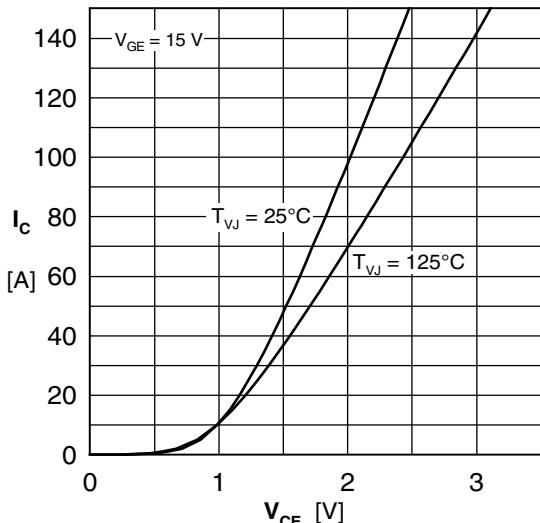


Fig. 1 Typ. output characteristics

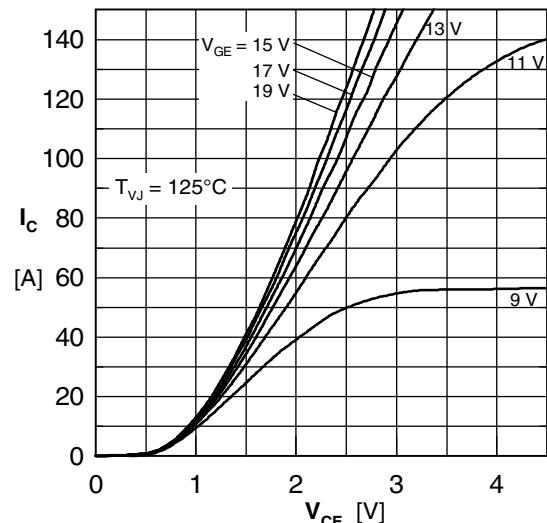


Fig. 2 Typ. output characteristics

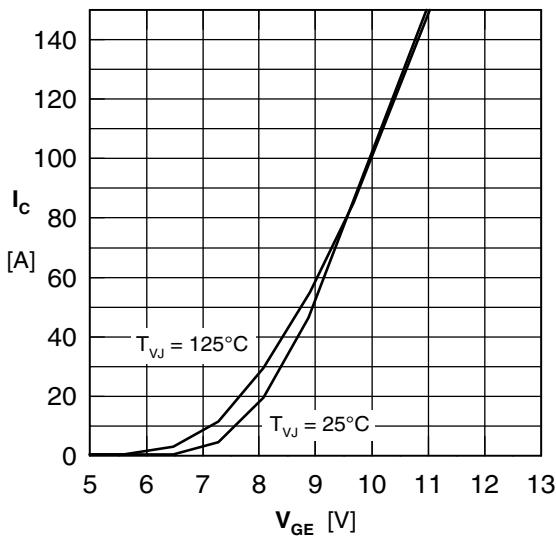


Fig. 3 Typ. tranfer characteristics

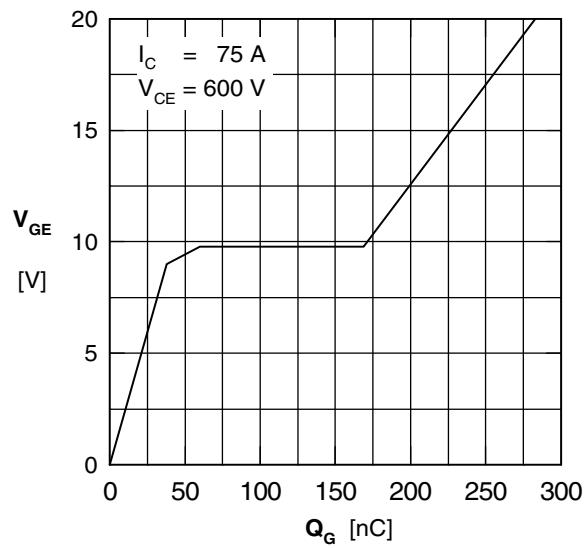


Fig. 4 Typ. turn-on gate charge

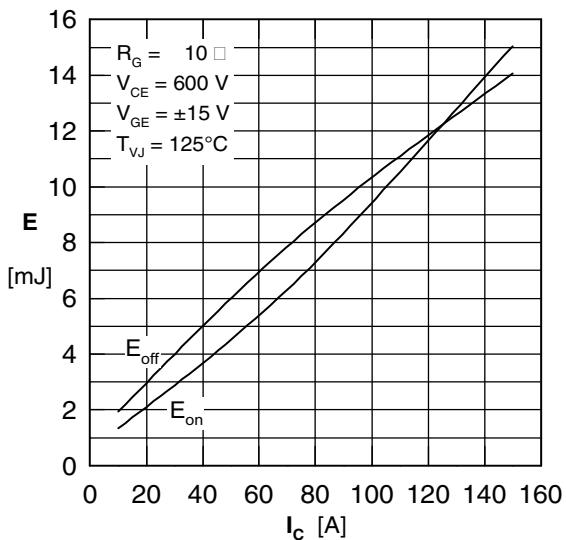


Fig. 5 Typ. switching energy vs. collector current

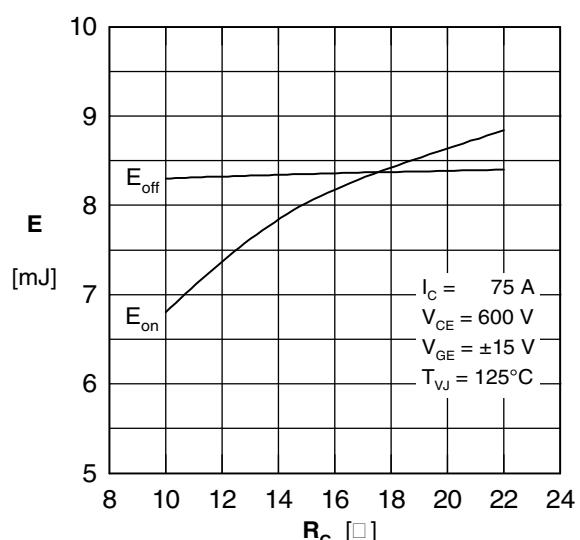


Fig. 6 Typ. switching energy vs. gate resistance

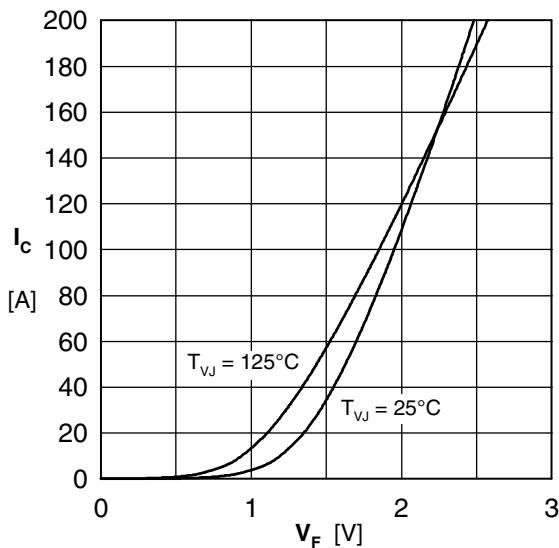


Fig. 7 Typ. forward characteristic

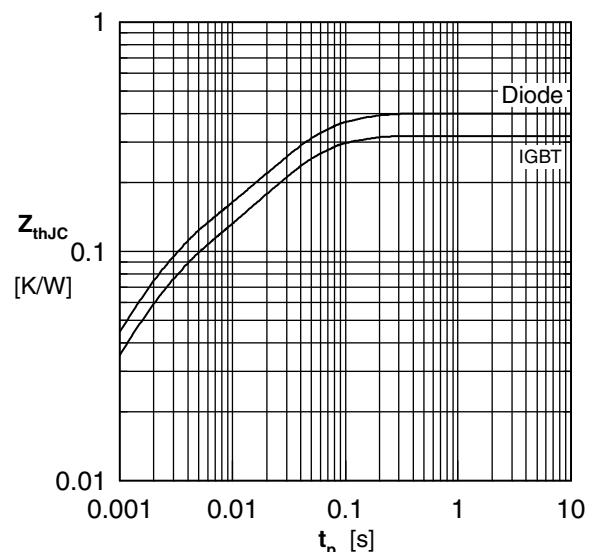
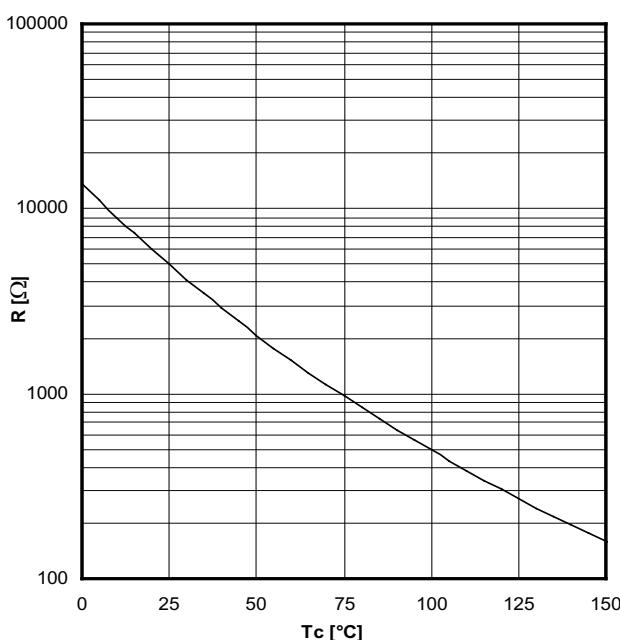


Fig. 8 Typ. transient thermal impedance

	IGBT		FRD	
	R_i	τ_i	R_i	τ_i
1	0.072	0.002	0.092	0.002
2	0.037	0.03	0.067	0.03
3	0.156	0.03	0.155	0.03
4	0.055	0.08	0.086	0.08

NTC



Typ. NTC resistance versus temperature